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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/708,707	03/19/2004	MIN-LUNG HUANG	10789-US-PA	2706
31561	90 10/05/2004		EXAMINER	
JIANQ CHY	UN INTELLECTUAL P	PICARDAT, KEVIN M		
7 FLOOR-1, 1	NO. 100			
ROOSEVELT ROAD, SECTION 2			ART UNIT	PAPER NUMBER
TAIPEI, 100			2822	
TAIWÁN				

Please find below and/or attached an Office communication concerning this application or proceeding.

	· ·- <u>- · · · · · · · · · · · · · · · · </u>	Application No.	Applicant(s)			
		10/708,707	HUANG ET AL.			
	Office Action Summary	Examiner	Art Unit			
		Kevin M. Picardat	2822			
Period for	The MAILING DATE of this communic	cation appears on the cover shee	t with the correspondence ac	ddress		
A SHORTHE MA - Extension after SIX - If the period of the	RTENED STATUTORY PERIOD FOR AILING DATE OF THIS COMMUNICATION of time may be available under the provisions of (6) MONTHS from the mailing date of this communication for reply specified above is less than thirty (30 priod for reply is specified above, the maximum states or reply within the set or extended period for reply by received by the Office later than three months after that the patent term adjustment. See 37 CFR 1.704(b).	CATION. of 37 CFR 1.136(a). In no event, however, mainication. of days, a reply within the statutory minimum of autory period will apply and will expire SIX (6) will, by statute, cause the application to become	ay a reply be timely filed If thirty (30) days will be considered time MONTHS from the mailing date of this one ABANDONED (35 U.S.C. § 133).			
Status		•				
2a)☐ Ti 3)☐ S	esponsive to communication(s) filed his action is FINAL . 2 ince this application is in condition for sed in accordance with the practic	b) This action is non-final. or allowance except for formal n		e merits is		
Disposition	n of Claims					
4a 5)□ C 6)☑ C 7)□ C	laim(s) <u>1-21</u> is/are pending in the apply Of the above claim(s) is/are laim(s) is/are allowed. laim(s) <u>1-21</u> is/are rejected. laim(s) is/are objected to. laim(s) are subject to restrict	e withdrawn from consideration.				
Application	n Papers					
10)⊠ Th Al R	ne specification is objected to by the ne drawing(s) filed on 19 March 200 oplicant may not request that any object eplacement drawing sheet(s) including the oath or declaration is objected to	4 is/are: a)⊠ accepted or b)□ tion to the drawing(s) be held in abe the correction is required if the draw	eyance. See 37 CFR 1.85(a). ving(s) is objected to. See 37 C	FR 1.121(d).		
Priority und	der 35 U.S.C. § 119					
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachment(s)						
2) Notice o	f References Cited (PTO-892) f Draftsperson's Patent Drawing Review (PT tion Disclosure Statement(s) (PTO-1449 or F o(s)/Mail Date	O-948) Paper	ew Summary (PTO-413) No(s)/Mail Date of Informal Patent Application (PT	O-152)		

DETAILED ACTION

Priority

Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-21 are rejected under 35 U.S.C. 102(b) as being anticipated by Tan et al. US 6,372,622.

Tan et al. discloses a wafer bumping process and the product made including providing a wafer (10), the wafer having a plurality of bonding pads (12) and a passivation layer (11) covering a surface of the wafer and exposing the pads, forming a first under bump metallurgy (14) layer covering the passivation layer and the bonding pads, forming a first patterned photoresist layer (20) on the first UBM layer, the first resist layer including a plurality of first openings corresponding to the pads and exposing a portion of the first UBM layer, forming a second UBM layer (30) within the first openings, forming a resist layer (40) on the first resist layer, the second resist layer including a plurality of second openings which are larger than the first openings to expose a portion of the second UBM layer, filling the second openings with a solder material (60), wherein the solder material covers the exposed portion of the second

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UBM layer, reflowing the solder material, removing second resist and first resist to expose a portion of the first UBM layer, and removing the exposed portion of the first UBM layer (see figs. 2-8 and related text). Tan et al. also discloses the various materials which can be used for the UBM layers and the solder.

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kevin M. Picardat whose telephone number is 571-272-1841. The examiner can normally be reached on Monday-Thursday 7:00-5:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on 571-272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Kevin M. Picardat Primary Examiner Art Unit 2822